

SOT662-1

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 x 5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN20
Package type industry code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	20	-	

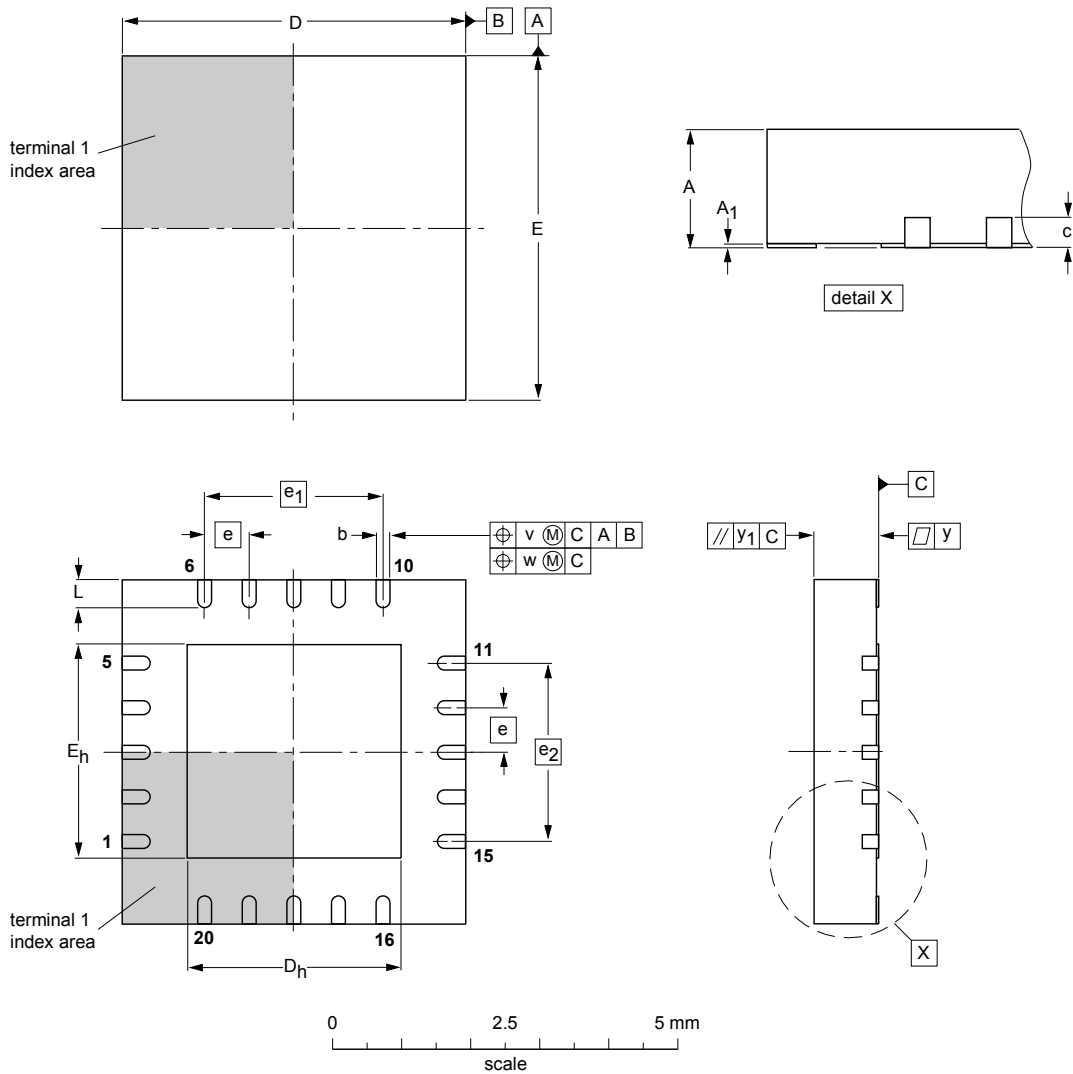


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2. Package outline

HVQFN20: plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 x 5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.38 0.23	0.2	5.1 4.9	3.25 2.95	5.1 4.9	3.25 2.95	0.65	2.6	2.6	0.75 0.50	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT662-1	---	MO-220	---			01-08-08 02-10-22

Fig. 1. Package outline HVQFN20 (SOT662-1)

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 x 5 x 0.85 mm

3. Soldering

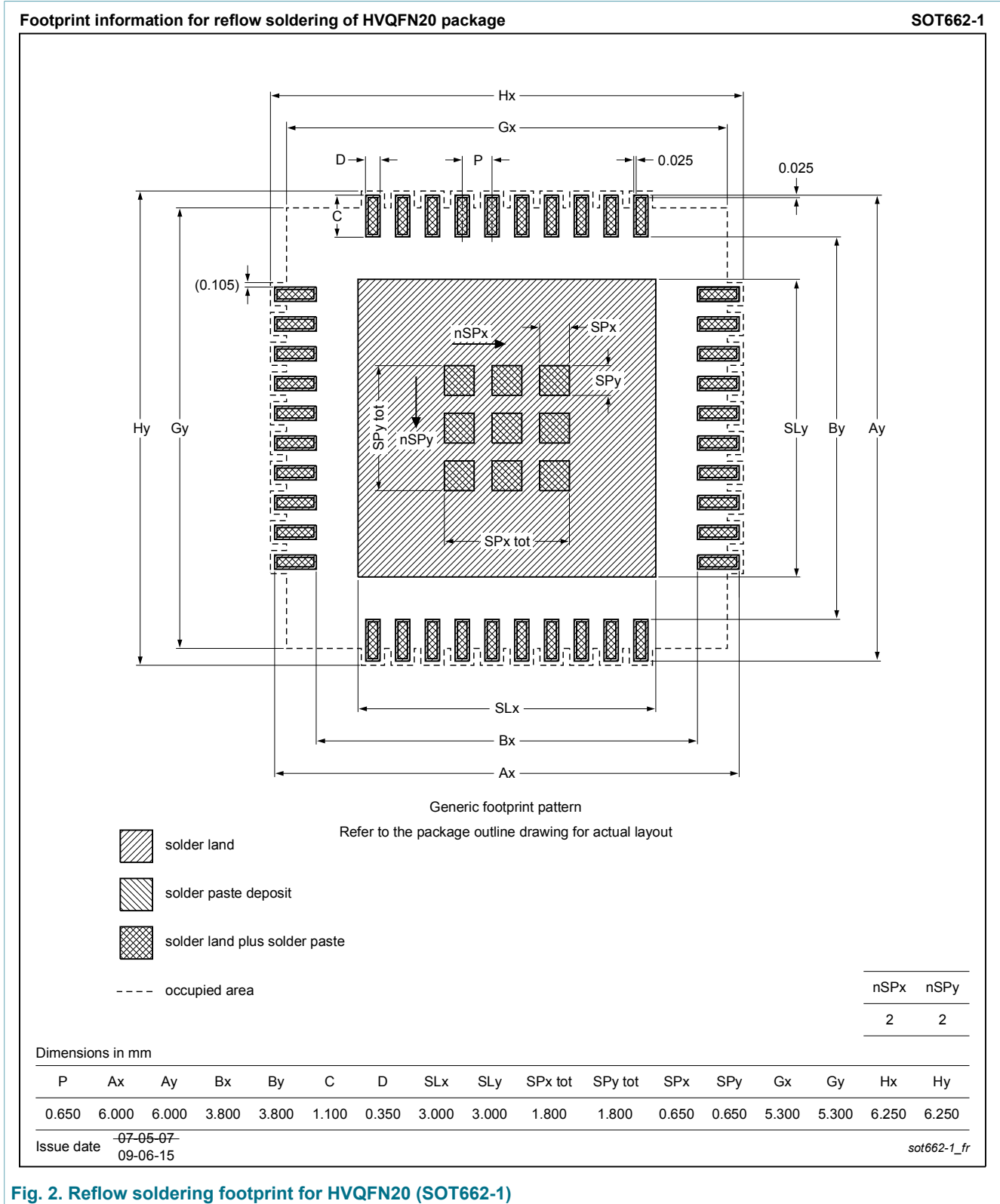


Fig. 2. Reflow soldering footprint for HVQFN20 (SOT662-1)

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4. Legal information

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